

03-21-2002

Form PTO-1595

(Rev. 03/01)

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U.S. DEPARTMENT OF COMMERCE  
U.S. Patent and Trademark Office

OMB No. 0651-0027 (exp. 5/31/2002)

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Lockheed Martin Corporation

3-21-02

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:



Assignment



Merger



Security Agreement



Change of Name



Other \_\_\_\_\_

Execution Date: December 21, 2001

## 2. Name and address of receiving party(ies)

Name: APT Group, Inc.

Internal Address: \_\_\_\_\_

Street Address: 1807 Kinglet Court

City: Costa Mesa State: CA Zip: 92626

Additional name(s) & address(es) attached? ☐ Yes ☒ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application No.(s) \_\_\_\_\_

B. Patent No.(s) 4,858,072 4,918,335

4,937,658 4,937,659 4,955,131 4,918,691

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Kevin G. McBride

Internal Address: \_\_\_\_\_

Street Address: 555 West Fifth St. #4600

City: Los Angeles State: CA Zip: 90013

## 6. Total number of applications and patents involved: 6

7. Total fee (37 CFR 3.41).....\$ 240.00



Enclosed



Authorized to be charged to deposit account

## 8. Deposit account number: \_\_\_\_\_

DO NOT USE THIS SPACE

## 9. Signature.

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Kevin G. McBride

Name of Person Signing

Signature

3/19/02

Date

Total number of pages including cover sheet, attachments, and documents: 5

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231PATENT  
REEL: 012683 FRAME: 0169

## ASSIGNMENT

LOCKHEED MARTIN CORPORATION, a Maryland corporation ("LMC"), for good and valuable consideration, the receipt of which is hereby acknowledged, hereby sells, assigns, transfers and sets over to APT GROUP, INC., a California corporation ("APT"), all the right, title and interest in, to and under the following:

(A) The United States patents (and the inventions claimed thereby) set forth in Appendix A, attached hereto and forming a part hereof, and all patents and patent applications of foreign countries corresponding to said U.S. Patents, and LMC hereby requests and authorizes the issuing authority to issue any and all patents based on such patent applications to APT, as assignee of the entire interest, including all rights of re-issue, re-examination, extension, division or continuation, and the right to sue and recover any and all damages for infringement thereof including damages for past infringement (collectively, the "Listed Patents"), the same to be held and enjoyed by APT for its own use and for its successors and assigns to the full end of the terms of the Listed Patents as fully and entirely as the same would have been held and enjoyed by LMC if this assignment had not been made;

(B) Any and all of the following technical materials owned by LMC directly relating to the inventions embodied in the Listed Patents and existing as of the date hereof: (i) documentation, (ii) specifications; (iii) drawings, (iv) art work, (v) models, (vi) proofs of concept, and (vii) other data (collectively, "Materials");

(C) Any and all modifications, changes, improvements, betterments or enhancements to the inventions embodied in the Listed Patents, whether or not patentable as of the date hereof, which have been invented, developed or discovered by LMC (collectively, "Improvements"); and

(D) Any and all intellectual property directly related to and covered by the Listed Patents, and all technology that was developed in connection with the intellectual property covered by the Listed Patents regardless of whether such technology is disclosed in or claimed by the Listed Patents (collectively, "Intellectual Property").

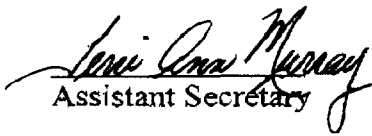
LMC hereby represents and warrants that it has good title to all of the Listed Patents, Material, Improvements and Intellectual Property assigned herein to APT free and clear of any liens, encumbrances, security interests, liabilities, agreements (other than any non-exclusive license in and to the Listed Patents which the United States government may have as a result of any funding that it may have provided for the development of the inventions embodied in the Listed Patents and the license granted to Ford Motor Company effective as of August 31, 1990), judgments, claims, or adverse rights whatsoever.

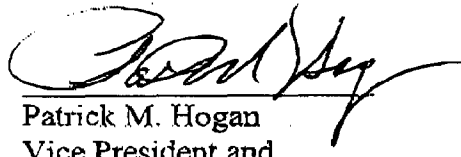
LMC hereby agrees for itself and its successor and assigns to execute any lawful document and to testify as to any material fact or thing which APT or its successors and assigns may deem necessary to secure unto itself or unto to its successors and assigns the full right, title and interest in and to the full enjoyment of the Listed Patents, Material, Improvements and Intellectual Property assigned herein to APT, or any part thereof, the same to be done without any further consideration.

LMC has caused its corporate seal to be affixed and this assignment to be executed by its duly authorized representative this 21<sup>st</sup> day of DECEMBER 2001.

LOCKHEED MARTIN CORPORATION

ATTEST:

  
Assistant Secretary

  
Patrick M. Hogan  
Vice President and  
Associate General Counsel

(SEAL)

**APPENDIX A**

| <b><u>U.S. PATENT NO.</u></b> | <b><u>TITLE</u></b>   |
|-------------------------------|---|
| 1. 4,858,072                  | Interconnection System for Integrated Circuit Chips                 |
| 2. 4,918,335                  | Interconnection System for Integrated Circuit Chips                 |
| 3. 4,937,659                  | Interconnection System for Integrated Circuit Chips                 |
| 4. 4,937,658                  | Interconnection System for Integrated Circuit Chips                 |
| 5. 4,955,131                  | Method of Building a Variety of Complex High Performance IC Devices |
| 6. 4,918,691                  | Testing of Integrated Circuit Modules                               |

**CANADIAN PATENT NO.**

|              |  |
|--------------|--|
| 1. 1,297,998 | Interconnection System for Integrated Circuit Chips  |
| 2. 1,319,202 | Method of Testing Integrated Circuit Device  |
| 3. 1,319,203 | Method of Building a Variety of Complex Integrated Circuits from Standardizable Components |
| 4. 1,319,204 | Universal Integrated Circuit Module  |
| 5. 1,319,205 | Modular Integrated Circuit Device  |

**EUROPEAN PATENT NO.**

|              |   |
|--------------|---|
| 1. 0 315 792 | Interconnection System for Integrated Circuit Chips |
|--------------|---|

**JAPANESE PATENT NO.**

|            |   |
|------------|---|
| 1. 2727204 | Interconnection System for Integrated Circuit Chips |
|------------|---|